

Amphenol

COMMUNICATIONS SOLUTIONS



www.amphenol-cs.com

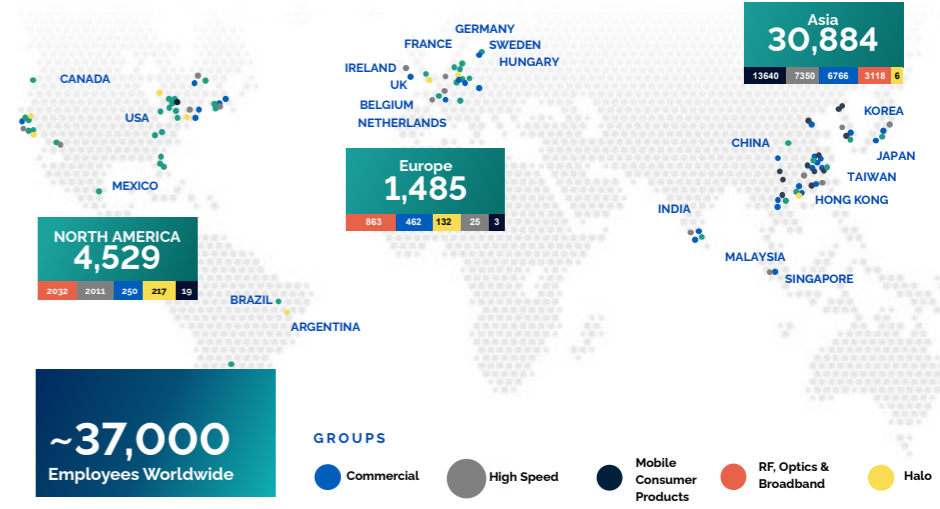
Amphenol

Amphenol Communications Solutions (ACS), a division of Amphenol Corporation, is a world leader in interconnect solutions for Communications, Mobile, RF, Optics, and Commercial electronics markets.

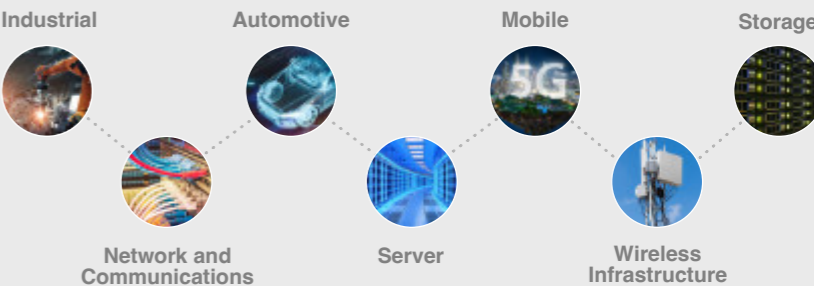
Amphenol Corporation is one of the world's largest designers and manufacturers of electrical, electronic and fiber optic connectors and interconnect systems, antennas, sensors and sensor-based products and coaxial and high-speed specialty cable.

ACS has an expansive global presence in research and development, manufacturing, and sales. We design and manufacture a wide range of innovative connectors as well as cable assemblies for diverse applications including server, storage, data center, mobile, RF, networking, industrial, business equipment and automotive.

Strong Global Presence



Application and Market Solutions



Custom Capabilities

Our engineering teams collaborate with our customers on thousands of projects every year, so no matter what technical, operational and even commercial challenges you face, Amphenol Communications Solutions can develop a solution for you!

www.amphenol-cs.com

Product Overview



www.amphenol-cs.com/high-speed-backplane



www.amphenol-cs.com/cables/backplane.html



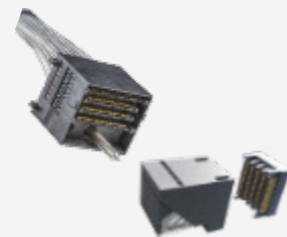
Paladin HD®

- Density optimized performance beyond 112G PAM4; roadmap to 224G
- Achieves 144 diff pairs within 1U Orthogonal slot
- Consistent signal integrity performance over the entire mating range
- Flexible architecture supports right angle female, direct orthogonal, and cables up to 12P



Paladin®

- Supports data rates beyond 112G PAM4; industry leading signal to noise performance
- Consistent signal integrity performance over the entire mating range
- Flexible architecture supports direct orthogonal, traditional backplane, mezzanine, coplanar and cable requirements up to 8P



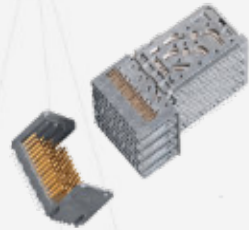
ExaMAX®

- Cost optimized with scalable performance to 112G PAM4
- Innovative design supports low insertion/extraction forces along with reduced crosstalk and low insertion loss
- Flexible architecture supports direct orthogonal, traditional backplane, coplanar and cable requirements



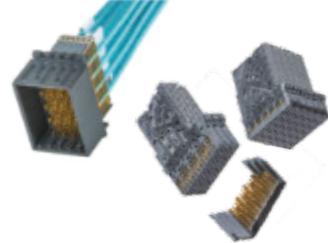
ExaMEZZ®

- Cost optimized with scalable performance up to 112G PAM4
- Innovative design supports low insertion/extraction forces along with reduced crosstalk and low insertion loss
- Stacked height range from 15 to 45mm in 2- and 4-Pair Configurations 14.5 to 67mm in 2- and 4-and 8-Pair configurations



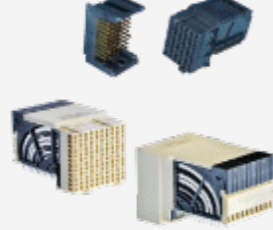
XCede® HD

- Supports designs from 8G to 56G PAM4
- The de facto standard for high performance backplane designs with industry leading density
- Supports Embedded Capacitors



XCede®

- Supports designs from 8G to 56G PAM4
- Scalable and flexible design supports all your system requirements
- Supports Embedded Capacitors; mechanically robust



AirMax®

- Cost optimized with scalable performance up to 56G PAM4
- Traditional backplane offering including standard and inverse gender
- Standard is 3-, 4- and 5-Pair



www.amphenol-cs.com/high-speed-io



UltraPort®/ ExtremePort® SFP

- Supports designs from 28G, 56G PAM4 & 112G PAM4
- Backwards compatible with SFP28
- Passive & active cables available in all 4x form factors; 26AWG to 32AWG cable
- Stacked, ganged and belly-to-belly board connector and cage configurations with heat sinks and light pipes



UltraPort®/ ExtremePort® QSFP

- Supports per port designs from 100G, 200G and 400G PAM4
- 4 lanes per cable – 28G, 56G and 112G per lane capability
- Passive & active cables available in all 4x form factors; 26AWG to 32AWG cable
- Stacked, ganged and belly-to-belly connector and cage configurations



ExtremePort® QSFP DD

- Supports per port designs from 200G, 400G and 800G PAM4
- 8 lanes per cable – 28G, 56G & 112G per lane capability
- Double the bandwidth per port vs. QSFP
- Backwards plug compatibility with QSFP; available in all 4x form factors



ExtremePort® OSFP

- Supports per port designs from 200G, 400G and 800G PAM4
- 8 lanes per cable – 28G, 56G & 112G per lane capability
- Thermal management engineered into cabled solution; available in all 4x form factors
- PAM4 modulation providing solutions up to 800G aggregate bandwidth



Mini-SAS HD External Connectors

- Capable of speeds up to 24Gb/s per channel (4 lanes, 8 lanes, 16 lanes available)
- Supports SAS 4.0 and PCIe Gen 4.0 applications
- 32Gb/s for PCIe Gen 5.0 solution in development



Mini-SAS HD Active Optical Cables

- Capable of speeds up to 16Gb/s per channel (4 lanes)
- Supports SAS 2.1, 3.0, 4.0 and PCIe Gen 3.0/4.0
- Transmission distance up to 100m (MMF)



200G QSFP DD Active Optical Cables

- Capable of speeds up to 25.78125Gb/s or 28.056Gb/s per channel (8 lanes)
- Supports 200G Ethernet NRZ
- Maximization of linear port density



400G QSFP DD Active Optical Cables

- Capable of speeds up to 56Gb/s per channel (8 lanes)
- Supports Ethernet PAM4
- Maximization of linear port density



100G QSFP Active Optical Cables

- Capable of speeds up to 25.78125Gb/s or 28.056Gb/s per channel (4 lanes)
- Supports 100G Ethernet and Infiniband 4xEDR and 4x32 FC protocols
- Transmission distance up to 100m (MMF)



300G CXP2 Active Optical Cables

- Capable of speeds up to 25.78125Gb/s per channel and 25Gb/s per channel (12 lanes)
- Supports Ethernet (25.78125Gb/s per channel) and Cpri (25Gb/s per channel) protocols
- Up to 300Gb/s aggregate bandwidth per channel



Leap® On-Board Transceiver

- 300Gb/s aggregate 12TRx at distances up to 70m
- Capable of speeds up to 28Gb/s per channel
- Low power consumption: 5.4W
- Small form factor: 1sq inch



SCFF On-Board Transceiver

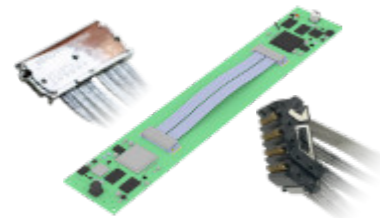
- 1TRx at up to 28Gb/s at distances up to 70m
- Duplex LC optical port
- SMT solder and 2-screw PCB fixation



External High Speed IO

On package or near ASIC to external IO receptacles

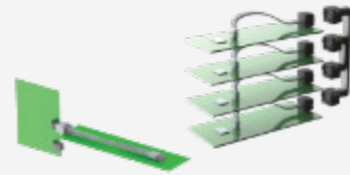
- Fully compliant to established industry standard interfaces: SFP, QSFP, QSFP DD, OSFP and others
- Supports transmission speeds of 28G, 56G and 112G per lane
- Press fit or cabled sideband signal management; engineered wire management
- Stacked, ganged, and belly-to-belly configurations coupled to high density (DP/mm²) near chip and on chip solutions



Internal High Speed IO

Near ASIC to card's or board's location in system

- Delivering a simple, low-loss, direct link to pluggable modules or anywhere in the system
- Optimization of low loss twinax cable with connectors including Mini-SAS HD, OCulink, SlimSAS™, Mini Cool Edge IO, ExtremePort™ Z-Link, Flash & Swift
- High speed, low profile and high density (bandwidth / mm²) near chip and on package solutions including micro-LinkOVERTM and DensiLinkTM
- Solutions available at 28G, 56G, 112G and 224G signaling speeds
- Multiple cable exit options including straight, right angle, and coplanar
- Construction options including double ended, Y, and breakout cables



Cabled Backplane

Near ASIC to system backplane or coplanar cards

- Cable Backplane System portfolio products extend the reach of passive copper for next generation system designs
- 56G and 224G PAM4 performance
- Optimization with our high speed, low loss twinax cable with Paladin® and ExaMAX® backplane connector families
- Flexible connector architecture supports cable blind mating with a backplane cable, press fit headers, right angle and orthogonal configurations



High Speed Bulk Cables

High frequency SkewClear EXD cable technology

- Offerings include multi-pair cables: 2, 4 and 8 pair constructions in wire gages from 32 AWG to 26 AWG (34 AWG in development)
- Supports transmission speeds of 10G, 28G, 56G, and 112G PAM4 per lane bandwidths
- Impedance tuned designs support: Paladin®, ExaMAX®, ExaMAX+®, micro-LinkOVERTM, Swift, Flash, GenZ, OverPass™ HSIO
- FEP insulated wiring for higher temperature environments



1G-10G Transceivers

- LR, ER, BIDI, CWDM, LWDM, DWM, etc
- SFP, SFP+, CFP, XFP
- C-TEMP, I-TEMP
- Tunable



25G Transceivers

- AOC, BIDI, SR, LR, ER
- DWDM, BIDI LR, BIDI ER, CWDM
- C-TEMP, I-TEMP



40G Transceivers

- SR, LR, ER, CWDM, AOC
- QSFP+
- C-TEMP, I-TEMP



50G Transceivers

- SFP56
- SR/eSR, FR, LR;
- C temp, I-temp



100G Transceivers

- QSFP28, CFP, CFP2, CFP4
- AOC, SR4, LR4, ER4 LITE, CWDM4
- C-TEMP, I-TEMP



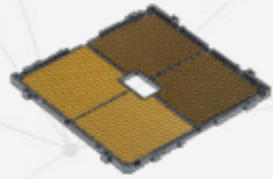
400G Transceivers

- QSFP DD
- FR4, DR4, SR8
- Ask about availability



16G / 32G / 64G Fibre Channel Transceivers

- EWRAP and OWRAP
- loopback designs
- C Temp and I Temp on some models
- Ask about availability



cLGA® High Speed Sockets

- Mechanically robust compression technology supporting designs with pin counts up to 10,000+ and 56 Gb/s+ data rates
- High performance configurations available in both LGA/LGA and LGA/BGA form factors



Chameleon®

- Delivers solid and proven 25 Gbps performance in real systems
- Allows maximum bandwidth while maintaining signal integrity



cStack™

- Configurable low profile compression solution available on .6mm to 1.27mm pitch in LGA/LGA and LGA/BGA form factors
- Ideal for board to board and module to board applications



Lynx™ QD

- Designed in multiple form factors: right angle, coplanar and vertical stacker
- Optimized for differential pair signaling to support PCIe Gen5 and 56G performance



cStack™ & Custom Flex

- Designed for applications where flexibility, space, weight and performance are critical
- Available with BGA, LGA, SMT, press-fit or thru-hole connector



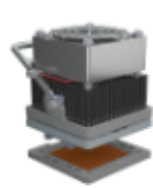
M-Series™ 56

- Designed to support high technology products in board-to-board or flex assembly architectures from 4-15mm
- Next-generation differential pair contact design for 56G NRZ, 112G PAM4 performance



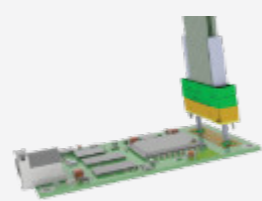
QSFP DD / OSFP Host Compliance Test Fixtures (HCTF)

- Full 16 differential pair access
- 1.85 mm test points meet both IEEE 802.3 and CEI 112G/lane requirements
- Each lane carefully matched through coax and PCB structures to ensure that the insertion loss and skew are constant for the entire unit



SK Series sockets

- Socket can be easily mounted and de-mounted with a few screws encouraging re-use across board revisions
- Durable 40 GHz+ socket solutions offer low loss connection for high performing devices



TR Multicoax Series

- Superior signal integrity up to 90 GHz
- Solderless system eliminates signal distortion for clean signal integrity
- Multiple form factors and channel counts available



CA Series Connectors and Interposers

- Bandwidth and performance beyond 32 Gb/s
- Pure vertical interface, no offset required
- No lost solder-down components on board revisions



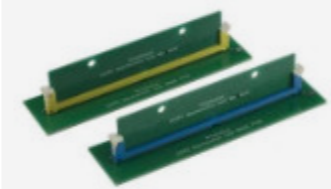
Mini Cool Edge for GEN Z/EDSFF/OCF

- 0.60mm pitch connector, supports high speed up to 112G PAM4
- Designed to meet SFF TA1002, Gen Z, EDSFF, OCF NIC 3.0 specifications
- Vertical, right angle, straddle mount and orthogonal options are available



PCIe® M.2 Gen 5 and Gen 4

- 67 contacts on 0.50mm pitch fully compliant with PCI-SIG PCIe® M.2 specification
- Dual Stacked, Shielded versions are available
- Right angle, vertical and various connector heights and keying options offered



DDR SMT Memory module Connectors

- Designed to meet JEDEC SO-016, SO-017, SO-019 and SO-023 specs
- U DIMM/R/LR Socket, Metal tab, Standard/Narrow/ latch available



Double Density Cool Edge for Ultra Compact Design

- 0.80mm pitch, power and signal hybrid connector
- Highly configurable wafer design for differential, single-ended and power options
- Supports high speed of up to 32GT/s (or 56GT/s PAM4) capability



PCIe® Gen4 and Gen5

- X1, X4, X8, X16, X24, X32 standard links
- 1.00mm pitch, vertical and right angle with options for ridge, locked latch, side latch, blade hold down, open wall
- Extensive range include options for surface mount, through-hole solder, press-fit and straddle mount terminations and keying options offered



PSAS, SAS and SATA Connectors

- SAS connectors (29-pins) support hot plugging and blind mating of HDDs/SSDs. 2 signal lanes support up to 24Gb data rate (SAS 4.0).
- PSAS connectors (68pins) support SAS HDD and NVME SSDs with 2 SAS lanes supporting up to 24G data rate and 4 PCIe lanes supporting up to 32G (PSAS 5.0) data rates.



Slim Cool Edge for High-Speed Hybrid Design

- 0.65mm pitch one-piece support high speed, sideband and power hybrid solution
- Supports high speed up to 32GT/s (or 56GT/s PAM4) capability
- Supports up to 330pin maximum



PCIe® Flip CEM, Slim CEM, Direct Cable Solution

- Flip CEM with "JJ" contact or "LL" contact provides better support for card edge to save keep out area for routing as compared to standard PCIe CEM contact of "JL".
- Standard PCIe CEM footprint is 8.2mm, Slim CEM is 7.45mm, Flip CEM is 5.9mm
- Direct Cable CEM features high-speed signal pins that directly attach to cable ends to save PCB loss



Compression, Board to Board Connectors and Interposer

- Provides a connection between either two PCB modules or one PCB and an electrical module
- Single-piece compression-type or two-piece board-to-board surface mount connectors



Standard Cool Edge 0.8mm for Automotive and 5G Antenna

- Robust design with EMI shielding for Automotive Ethernet and Power applications
- Hybrid option for small cell active antenna BTB application
- One-piece small form factor to save space



DDR5 SO-DIMM Connectors

- 262 positions connector in high-density design of 0.50mm pitch
- 4.00mm, 8.00mm, 5.20mm and 9.20mm height
- Right angle and vertical orientation with SMT mechanical hold-downs



High mating cycle connectors for Test and Measurement Equipment

- Supports 100k cycle mating/unmating – Ideal solution for test and measurement equipment.
- Non-soldering type allows replacement of connector without damaging the main PCB after 100,000 cycles
- Supports DDR5 data rate



Ve-NET™

- Developed according to USCAR-2 & LV214
- Using twisted pair cables to transmit data rates up to 50Gb/s
- Supports Automotive Ethernet, LVDS, APIX3, and FPD-Link IV



ExtremePort™ Z-Link

- Compliant with Gen-Z and OCP NIC specifications. SFF-TA-1002/1020 solution
- High speed of up to 56Gb/s PAM4
- Supports both cable and card edge applications



Fan Connectors

- Blind-Mate Interface Wire to Board connectors from 1.25mm to 2.54mm pitch with max current rating 5.5A/pin. Designed for Server and Storage applications
- Card to Wire connectors in 2.44mm and 2.54mm pitch with current rating 4A/pin. Designed for Switch application



HSbridge+

- Connectors with headers compliant with USCAR-30 USB and USCAR-2
- High data rate up to 10Gb/s, current rating up to 5 amps of power output
- Color coding effectiveness compliant with automotive requirements



ExtremePort™ Swift Link

- Ultra-low profile, 0.60mm pitch connector in 8X, 16X configurations. Mating height 8.38mm
- Designed for unshielded, internal I/O connectors
- With 85Ω impedance and meets PCIe® Gen 5 NRZ 32G specifications



Power Connectors

- Wire to Board connectors in 3.0 mm and 4.2mm pitch with current ratings from 6.5A to 20A per pin
- Designed for IT and Datacom applications



Mini Cool Edge IO

- Up to 64Gb/s PAM4, PCIe® Gen 4, PCIe® Gen 5, PCIe® Gen 6, over 1.0 meter transmission distance
- 0.60mm pitch connectors support both cable and card edge connections
- Options for 92Ω, 85Ω and 95Ω impedance and various pin number options - meeting PCIe®/NVMe/SAS/SFP(+)/QSFPP specifications



USB Type-C Connectors

- Performs to USB4 and Thunderbolt4 high-speed specifications, and backward compatible with USB3.2 Gen1 and Gen2
- Waterproof versions featuring unique O-ring technology (LIM) perform up to IPX8
- Supports up to 240W (5A/48V) power supply



SD/Micro SD Express Series Connectors

- PCIe Gen3*1/ Gen4*1 lane
- Backward compatible to UHS-I/ UHS-II in one socket (3-in-1 solution)
- Push push/push pull structure



Multi-Trak™

- Combines original PCIe® and Mini Cool Edge IO in one connector to provide both power (21A) and high/low-speed signal
- Up to 56Gb/s PAM4, PCIe® Gen 5, and target PCIe® Gen 6
- Options for 85Ω impedance and various pin number options - meeting PCIe®/NVMe/SAS/OCPC DC-MHS/ SFF-TA-1033 specifications



RJMG

- 10/100T, 1GBT (10/100/1000-BT), 2.5G, 5G, 10G, Power Over Ethernet (PoE, 15W~150W), integrated with surge protection.
- Commercial 0~70°C and industrial -40~85°C & -40~105°C .
- Meets IEEE802.3ab and supports various Ethernet PHY



DisplayPort 2.1 Connectors

- DP2.1, UHBR20, 80Gbps/4 Lanes, 85ohm, for DP80 cable
- Backward compatible to DP1.4 footprint.
- Optional for flange and plastic post.



BarKlip® BK500 IO

- Distributes up to 500A per contact
- Simple configurable plug-and-play solutions
- Fully compliant with ORv3 Power Output Specifications



PwrBlade® ULTRA HD

- Up to 85A per contact
- 2.0mm high density signal pitch
- Ultra-low profile height of 9.6mm above board for optimized airflow



SheerPwr®

- Available in 3.6mm, 6.0mm, and 8.0mm pin diameter options
- Large beam deflection range handles up to ±0.40mm of permanent misalignment
- Low 6.80mm connector height



BarKlip® BK150 IO

- Distributes up to 150A per contact between busbars, cables, and circuit boards
- Simple configurable plug-and-play solutions
- Fully compliant with ORv3 IT Gear Power Input Solution Specifications



PwrBlade+® IO

- Up to 60A per contact (high power) & 25A per contact (low power)
- Power & signal contacts are highly configurable
- Wide range of wire sizes available



CoolPower® SDM

- Up to 35A per pin, high current Coolband contact technology
- Backplane, coplanar, and orthogonal configurations available
- 2 position or 4 position available



AC Input Connector and Cable Assemblies

- 7-Pin connector designed for Star, Delta, and single-phase connections
- Simple configurable plug-and-play solution designed to meet various current and voltage ratings
- Fully compliant with OCP ORv3 Power Shelf Universal Input Connect Specifications



BarKlip® XP300/XP200

- Current ratings up to 300A and 200A
- Mates with 3.0mm busbar
- ±2.0mm gatherability



EnergyEdge™ X-treme

- 3000W at 12V
- Available in straddle mount, right angle, right angle coplanar, and vertical configurations
- 25% increase in current linear density



PwrBlade® MiniMezz

- Up to 50A per contact (high power) and 25A per contact (low power)
- Available stack heights range from 8mm to 20mm (tooled in 1mm increments)
- +/- 0.80mm gatherability for blind mate applications



BarKlip® BK200 IO for EV Charging

- Distributes up to 200A per contact
- 14 independent conducting beams with silver plating
- Ultrasonically welded between wire and contact



PwrMAX® G2

- Highest density blind-mate Power and Signal connector series
- Up to 130A per contact and 18% size reduction
- Orthogonal, mezzanine, coplanar and right-angle configurations available for both PCB and busbar applications



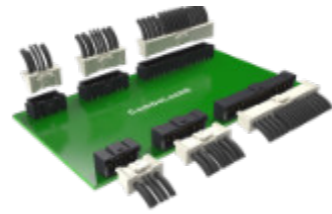
Minitek MicroSpaceXS™ 1.27mm

- Compact, robust and versatile
- LV214 Severity-3, USCAR-T2V2 compatible
- 4A per contact, TPA, CPA features



Minitek MicroSpaceXS™ Waterproof 1.27mm

- LV214 Severity-3, USCAR-T2V2 compatible
- IP68
- 3A per contact, TPA, CPA features



ComboLock® 1.00mm/3.00mm

- Compact, hybrid wire-to-board connector.
- Active Positive Latching
- 1.5A signal, 10A power



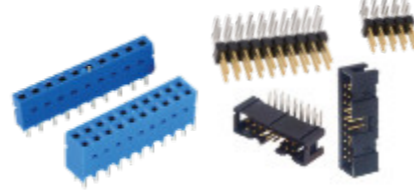
FlexLock® 2.54mm

- FPC system for easy assembly
- USCAR-T2V2 compatible.
- 3A per contact, TPA, CPA features



WireLock® 2.00mm

- Robust, low mating force
- USCAR-2 V2 compatible.
- 3A per contact, TPA, CPA features



Modular Systems 2.54mm/2.00mm

- Dubox®, Quickie®, BergStik®, PV® 2.54mm, Minitek® 2.00mm
- Industry proven connector system
- Board to Board, Wire/Cable to Board



MicroSpeed® 1.00mm

- Industrial grade reliability.
- Superior EMI, EMC performance
- Signal speed up to 25Gb/s.



ComboStak® 0.80mm / 2.00mm

- Hybrid and medium power solution
- 0.8A signal, 20A power
- Signal speed up to 12Gb/s.



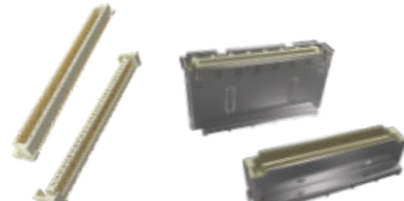
BergStak® 0.40mm Connector

- Fine pitch, vibration-proof.
- Wide range of positions.
- Signal speed up to 16 Gb/s.



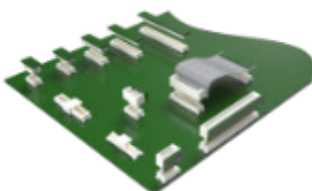
BergStak® Secure 1.00mm

- High security, high density
- EMI Shielding
- Speed up to 32Gb/s.



BergStak® 0.80mm

- Ideal for use in high density applications
- Wide range of positions and stack heights
- Speed up to 16 Gb/s.



Conan® 1.00mm

- Secure, reliable connector
- Audible "click" to ensure perfect mating
- Speed up to 8 Gb/s.



Minitek® Pwr Connector and Cable Assemblies

- Complete interconnect solutions for wire-to-wire and wire-to-board
- Available in pitch sizes of 3.00mm, 4.20mm and 5.70mm
- Current ratings from 5A to 28A



Minitek® Pwr CEM-5 PCIe® Connector System

- Newly launched CEM 5.0 PCI Express® 12VHPWR auxiliary hybrid connector and cable assembly solution
- Supports 600W GPU cards
- Rated current up to 9.5A per contact and features fully isolated terminals



Minitek® PICPwr OCP Connector Solutions

- Newly launched 12V connector solution supports Open Compute Project Power Distribution and Management architecture requirements
- Operating power and voltage is 864W at 12VDC



DuraEV™

- IP67 rated portable and fixed battery connectors for charging and discharging electric vehicles
- Robust and highly durable - provides continuous current of 70A and withstands 10,000 mating cycles



DuraSWAP™ Swappable battery connectors

- IP67 rated swappable battery docking connectors
- Contact system provides continuous current of 100A and withstands 10,000 Mating cycles
- Connector mates in four different orientations



Custom Battery Pack Connectors

- Robust battery pack charger connectors and terminal solutions for cordless power tools, lawnmowers, cordless vacuum cleaners, and personal care devices
- Available in various pin configurations and connector sizes with current ratings up to 45A.
- IP67 rated in both mated and unmated condition



Custom Industrial and Automotive Connectors

- Wide range of customized connector solutions from ECU connectors and sensor housings in automotive applications to circlip assemblies, board-to-board headers, interface modules and plug-in splitters in Industrial applications.



D-Sub Slimline

- Ultra slim body with contact alignment in a single row for significant saving in board space and with mating compatibility



OCTIS™ Outdoor IO

- Robust I/O for high reliability and performance



Industrial Backplane Connectors

- 2.00 mm Millipacs® series hard metric connector, 2mm Metral® series future bus connector & 2.54mm DIN 41612 connector for robust applications in the Industrial segment
- Features 2-beam twisted tulip contact which provides an equalized signal path



High Temperature Backplane Connectors

- Feature-packed connectors designed for use in higher operating temperature applications. Compliant to EN45545

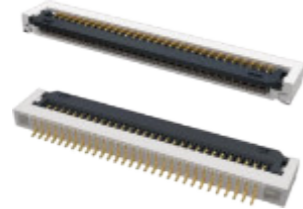


Millipacs® Plus

- Configurable meeting designers' choice of signal data rates from 3Gbps to 25Gbps and power up to 40A and with multiple guiding options
- Compliant to Hardmetric equipment practice and complimentary to 2mm Millipacs standard
- Options for Hotswapping, EMI shielding and high temperature

FFC/FPC Connectors with Autolock Mechanism

- 0.21mm, 0.50mm and 2.00mm pitch with heights from 0.5mm to 6.25mm
- One action operation and high retention force.
- Automotive grade connectors compliant with USCAR2 and LV214
- FFC cable can be supported as a whole solution



FFC/FPC Connectors

- From 0.21mm to 2.0mm pitch with various heights ranging from 0.5mm to 6.25mm.
- Easy to operate and high vibration-proof performance
- Automotive grade versions compliant with USCAR2 and LV214 are available
- FFC cable can be supported as a whole solution

FloatCombo™ Floating Board-to-Board Connector System with Power Pin

- 0.50mm pitch connector with 4 independent power pins
- Supports 5A current per power pin and high-speed data rates up to 16Gb/s
- Various stacking heights from 8mm to 30mm with large floating allowance
- USCAR-2 T3V2 qualified



Micro Board-to-Board

- Low profile and fine pitch for high density applications
- High current rating (Up to 5A)
- Chamfer connector design prevents mismatching

FlexFast™ Flex to Board Connector Solution

- Small size and low height flex to board connection solution.
- 0.45mm/0.75mm/0.9mm/1.5mm/1.8mm pitch. Pin counts from 12~100pin
- Automotive grade compliant to USCAR2 and LV214
- Designed for BMS, battery pack, Inverter+DCDC applications



Customized Solutions for Automotive and Consumer Applications

- Supports custom connector requirements with value-added solutions, minimal turnaround time, and competitive pricing

Lighting Connectors

- Lighting connectors & cables
- NEMA/ANSI C136.41
- Zhaga Book 18 and Book 20
- LED indoor, outdoor, street lighting applications

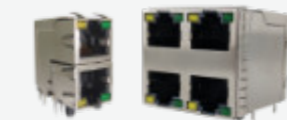


Ruggedized

- Ruggedized, IP67 sealed
- Connectors & cables
- RJ, USB, USB-C, D-Sub, HDMI
- MRD Circular latching
- FLH rectangular latching
- Industrial, commercial, lighting

ix Industrial Ethernet

- Next gen ruggedized interface
- IEC 61076-3-124, Cat6A, PoE++
- IP20 & IP67 connectors & cables
- ix-Mag with integrated magnetics
- Factories, Robotics applications



RJ / Modular Jacks

- Cat5, Cat5e, Cat6, Cat6A
- Single port, ganged, stacked multi-port, LEDs, shielded
- Vertical, right angle
- PoE++ capability
- Industrial, commercial, medical, consumer, military applications

Single Pair Ethernet

- Next gen ruggedized interface
- IEC 63171-6, PoDL
- IP20 & IP67 connectors & cables
- Industrial Ethernet to the sensor and actuator level



Industrial RJ Plugs

- Ruggedized RJ plugs & cables
- IDC termination, field installable
- Metal latching, full metal construction
- Cat6A, fully shielded
- Multiple cable entry angle options
- Factory and other applications

Amphenol

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